

[ABSTRACT]

A method for manufacturing a semiconductor chip includes steps (S1) to (S4) below in this order:

(S1) preparing a wafer for producing semiconductor chips, wherein groove parts as predetermined segmentation lines are formed in a bump-formed surface of a semiconductor wafer having the bump-formed surface provided with bumps, the groove parts not reaching a back surface of the semiconductor wafer;

(S2) attaching a first curable resin (x1) by pressing to the bump-formed surface of the wafer for producing semiconductor chips to cover the bump-formed surface of the wafer for producing semiconductor chips with the first curable resin (x1) and to embed the first curable resin (x1) into the groove parts formed in the wafer for producing semiconductor chips;

(S3) curing the first curable resin (x1) to obtain a wafer for producing semiconductor chips with a first cured resin film (r1);

(S4) segmenting the wafer for producing semiconductor chips with the first cured resin film (r1) along the predetermined segmentation lines into individual pieces to obtain semiconductor chips, wherein at least the bump-formed surface and a side surface are covered with the first cured resin film (r1); and

further includes step (S-BG) below after step (S2) above and before step (S3) above, after step (S3) above and before step (S4) above, or in step (S4) above:

(S-BG) grinding the back surface of the wafer for producing semiconductor chips.

Selected Drawing: Fig. 1